



## Material Content Data Sheet



<b>Sales Product Name</b>		BSL214N H6327		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001162318						
<b>Package</b>		PG-TSOP6-6-4		<b>Weight*</b>		14.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.03		280	
	noble metal	gold	7440-57-5	0.016	0.11		1085	
	inorganic material	silicon	7440-21-3	0.245	1.65	1.79	16545	17910
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		96	
	non noble metal	titanium	7440-32-6	0.007	0.05		479	
	non noble metal	chromium	7440-47-3	0.021	0.14		1436	
	non noble metal	copper	7440-50-8	7.048	47.66	47.86	476611	478622
wire	non noble metal	copper	7440-50-8	0.077	0.52	0.52	5218	5218
encapsulation	organic material	carbon black	1333-86-4	0.068	0.46		4617	
	plastics	epoxy resin	-	1.468	9.93		99256	
	inorganic material	silicondioxide	60676-86-0	5.290	35.78	46.17	357783	461656
leadfinish	non noble metal	tin	7440-31-5	0.392	2.65	2.65	26542	26542
plating	noble metal	silver	7440-22-4	0.149	1.01	1.01	10052	10052
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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